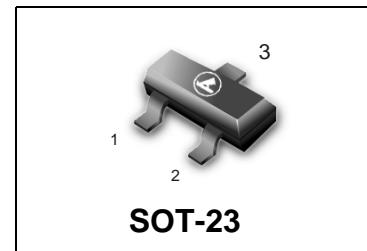


Power MOSFET 750 mAmps, 20 Volts N-Channel SOT-23

These miniature surface mount MOSFETs low $R_{DS(on)}$ assure minimal power loss and conserve energy, making these devices ideal for use in space sensitive power management circuitry. Typical applications are dc–dc converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low $R_{DS(on)}$ Provides Higher Efficiency and Extends Battery Life
- Miniature SOT-23 Surface Mount Package Saves Board Space

LMGSF1N02LT1



MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

| Rating | Symbol | Value | Unit |
|--|-------------------|-------------|--------------------|
| Drain-to-Source Voltage | V_{DSS} | 20 | Vdc |
| Gate-to-Source Voltage – Continuous | V_{GS} | ± 20 | Vdc |
| Drain Current – Continuous @ $T_A = 25^\circ\text{C}$ – Pulsed Drain Current ($t_p \leq 10 \mu\text{s}$) | I_D I_{DM} | 750 2000 | mA |
| Total Power Dissipation @ $T_A = 25^\circ\text{C}$ | P_D | 400 | mW |
| Operating and Storage Temperature Range | T_J, T_{stg} | -55 to 150 | $^\circ\text{C}$ |
| Thermal Resistance – Junction-to-Ambient | $R_{\theta JA}$ | 300 | $^\circ\text{C/W}$ |
| Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds | T_L | 260 | $^\circ\text{C}$ |

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|----------------------------|--------|-----|-----|-----|------|
| OFF CHARACTERISTICS | | | | | |

| | | | | | |
|---|---------------|----|---|-----------|---------------|
| Drain-to-Source Breakdown Voltage ($V_{GS} = 0$ Vdc, $I_D = 10 \mu\text{A}$) | $V_{(BR)DSS}$ | 20 | - | - | Vdc |
| Zero Gate Voltage Drain Current ($V_{DS} = 20$ Vdc, $V_{GS} = 0$ Vdc) ($V_{DS} = 20$ Vdc, $V_{GS} = 0$ Vdc, $T_J = 125^\circ\text{C}$) | I_{DSS} | - | - | 1.0 10 | μA |
| Gate-Body Leakage Current ($V_{GS} = \pm 20$ Vdc, $V_{DS} = 0$ Vdc) | I_{GSS} | - | - | ± 100 | nAdc |

DEVICE MARKING

LMGSF1N02LT1=N2

LMGSF1N02LT1
ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|----------------|--------|-----|-----|-----|------|
|----------------|--------|-----|-----|-----|------|

ON CHARACTERISTICS (Note 1.)

| | | | | | |
|---|---------------------|--------|----------------|----------------|------|
| Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$) | $V_{GS(\text{th})}$ | 1.0 | 1.7 | 2.4 | Vdc |
| Static Drain-to-Source On-Resistance ($V_{GS} = 10 \text{ Vdc}$, $I_D = 1.2 \text{ Adc}$) ($V_{GS} = 4.5 \text{ Vdc}$, $I_D = 1.0 \text{ Adc}$) | $r_{DS(\text{on})}$ | — — | 0.075 0.115 | 0.090 0.130 | Ohms |

DYNAMIC CHARACTERISTICS

| | | | | | | |
|----------------------|--------------------------------|-----------|---|-----|---|----|
| Input Capacitance | ($V_{DS} = 5.0 \text{ Vdc}$) | C_{iss} | — | 125 | — | pF |
| Output Capacitance | ($V_{DS} = 5.0 \text{ Vdc}$) | C_{oss} | — | 120 | — | |
| Transfer Capacitance | ($V_{DG} = 5.0 \text{ Vdc}$) | C_{rss} | — | 45 | — | |

SWITCHING CHARACTERISTICS (Note 2.)

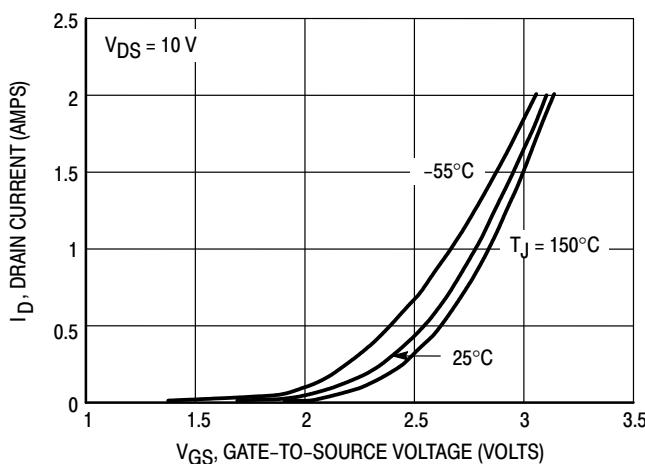
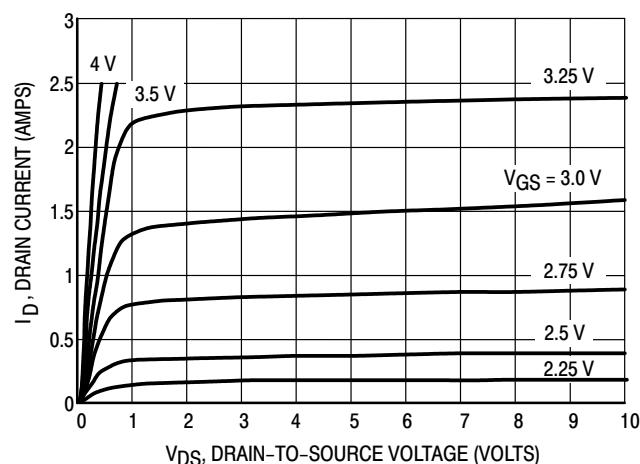
| | | | | | | |
|----------------------------|---|---------------------|---|------|---|----|
| Turn-On Delay Time | $(V_{DD} = 15 \text{ Vdc}, I_D = 1.0 \text{ Adc}, R_L = 50 \Omega)$ | $t_{d(\text{on})}$ | — | 2.5 | — | ns |
| Rise Time | | t_r | — | 1.0 | — | |
| Turn-Off Delay Time | | $t_{d(\text{off})}$ | — | 16 | — | |
| Fall Time | | t_f | — | 8.0 | — | |
| Gate Charge (See Figure 6) | | Q_T | — | 6000 | — | pC |

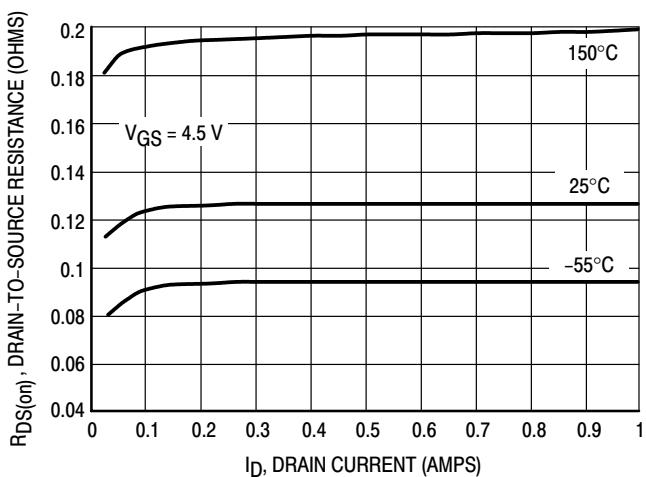
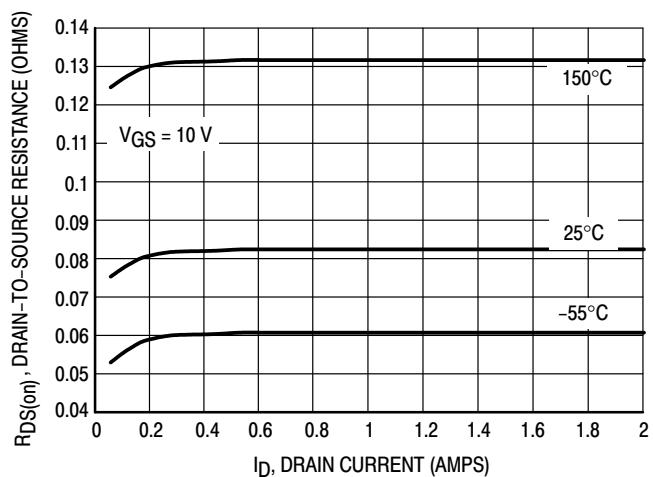
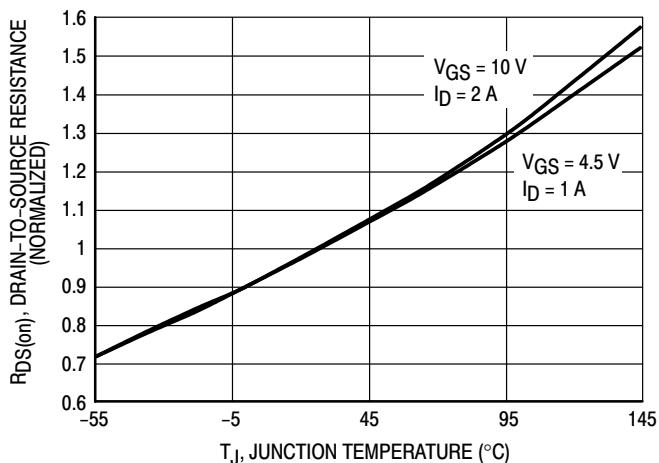
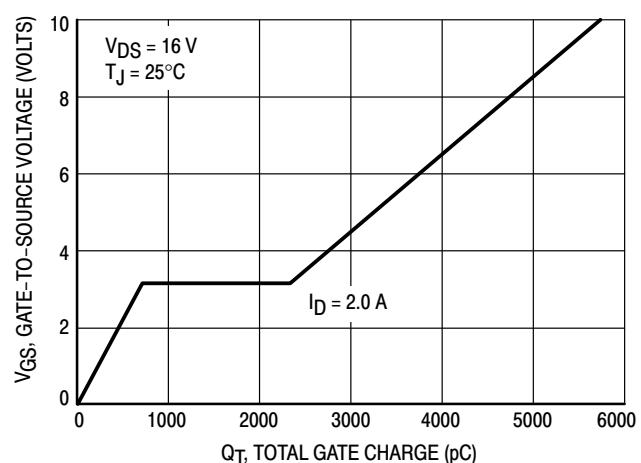
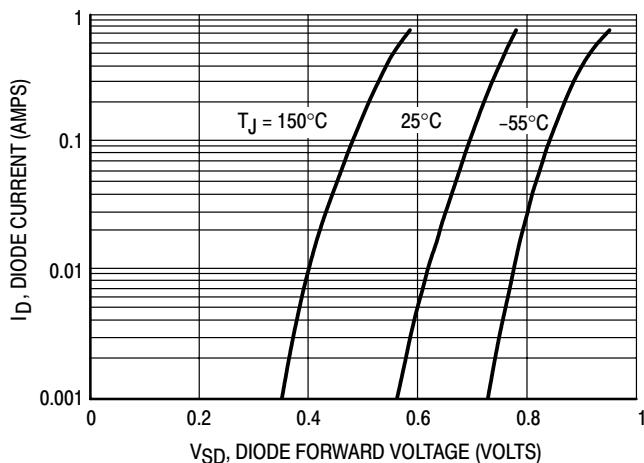
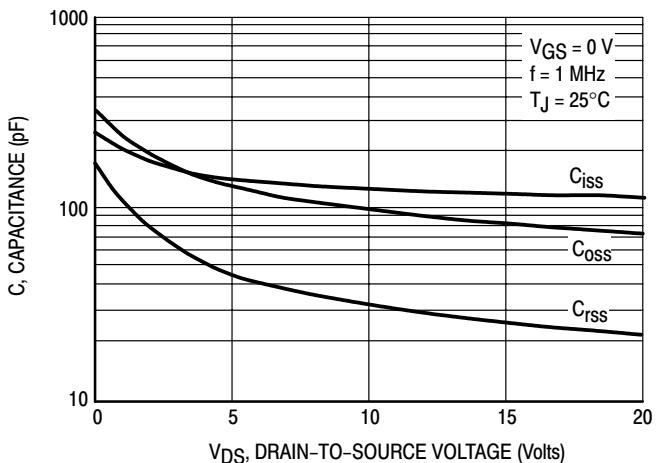
SOURCE-DRAIN DIODE CHARACTERISTICS

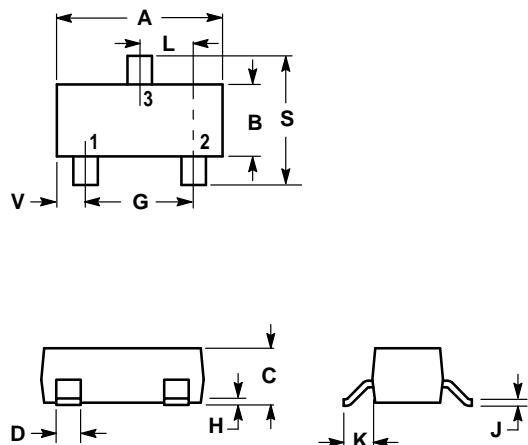
| | | | | | |
|---------------------------|----------|---|-----|------|---|
| Continuous Current | I_S | — | — | 0.6 | A |
| Pulsed Current | I_{SM} | — | — | 0.75 | |
| Forward Voltage (Note 2.) | V_{SD} | — | 0.8 | — | V |

1. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$.

2. Switching characteristics are independent of operating junction temperature.

TYPICAL ELECTRICAL CHARACTERISTICS

Figure 1. Transfer Characteristics

Figure 2. On-Region Characteristics

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Figure 3. On-Resistance versus Drain Current

Figure 4. On-Resistance versus Drain Current

Figure 5. On-Resistance variation with Temperature

Figure 6. Gate Charge

Figure 7. Body Diode Forward Voltage

Figure 8. Capacitance

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SOT-23

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

| DIM | INCHES | | MILLIMETERS | |
|----------|--------|--------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.1102 | 0.1197 | 2.80 | 3.04 |
| B | 0.0472 | 0.0551 | 1.20 | 1.40 |
| C | 0.0350 | 0.0440 | 0.89 | 1.11 |
| D | 0.0150 | 0.0200 | 0.37 | 0.50 |
| G | 0.0701 | 0.0807 | 1.78 | 2.04 |
| H | 0.0005 | 0.0040 | 0.013 | 0.100 |
| J | 0.0034 | 0.0070 | 0.085 | 0.177 |
| K | 0.0140 | 0.0285 | 0.35 | 0.69 |
| L | 0.0350 | 0.0401 | 0.89 | 1.02 |
| S | 0.0830 | 0.1039 | 2.10 | 2.64 |
| V | 0.0177 | 0.0236 | 0.45 | 0.60 |

PIN 1. BASE
2. Emitter
3. Collector

